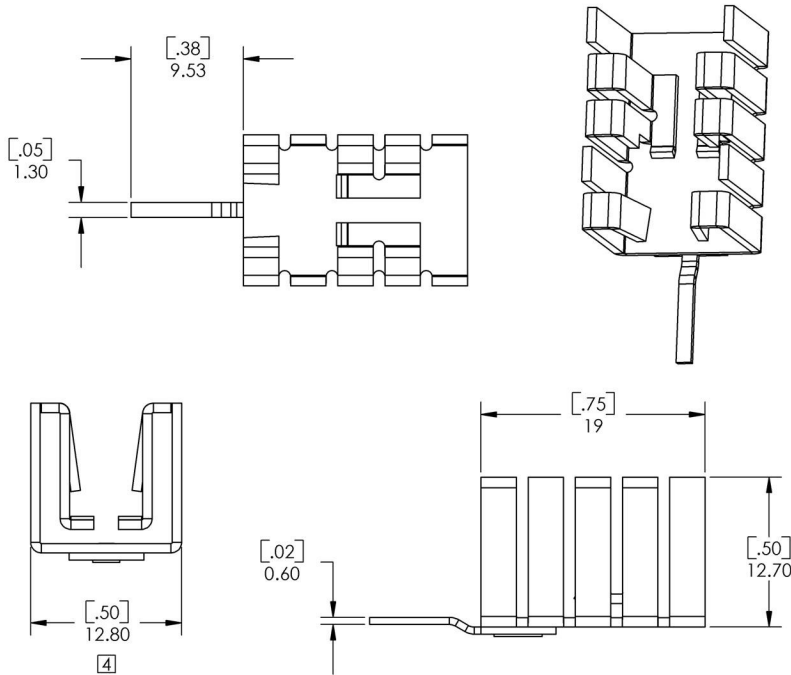
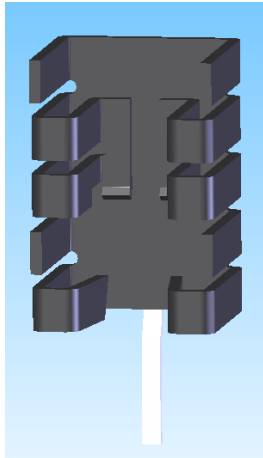


# Board Level Heat Sinks



ThermaFlo

P/N: 831502B03900



## PRODUCT SPECIFICATIONS

- Devices: TO-220 & TO-262
- Size: 19.0 x 12.8 x 12.7 mm
- Material: Aluminum, 1.2 mm Thick
- Type: Stamped
- IC Mounting: Integrated Spring
- PCB Mounting: Solderable Tab
- Finish: Black Anodized
- Package: Bulk

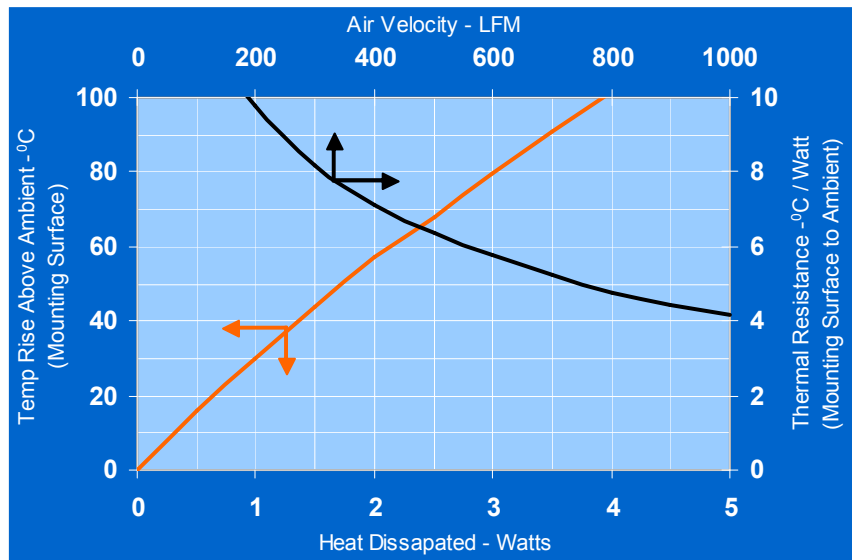
## FEATURES & BENEFITS

- No Hardware Device Attachment
- Constant Spring Force Tension
- Vertical Mounting via Solderable Tab
- RoHS Compliant



## CUSTOMIZED HEATSINKS

- Specialized Tabs, Plating
- Specialized Body Configurations
- Contact Applications Engineering



TO-220, TO-262

**COMAIR ROTRON, INC**  
 8929 Terman Court, San Diego, CA 92121  
 Ph (858) 348-6200 Fax (858) 566-4577  
 E-mail: sales@comairrotron.com,  
 Web: www.comairrotron.com